

	Type	L #	Hits	Search Text	DBs	Time Stamp	Com men ts	Er ro r De fi ni ti on	Er ro rs
1	BRS	L1	67	flexible with substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and (protect\$5 or solder near resist\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 13:20			
2	BRS	L2	0	(257/616).ccls. and flexible with substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and (protect\$5 or solder near resist\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 13:40			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Com men ts	Er ro r De fi ni ti on	Er ro rs
3	BRS	L4	13	flexible with substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and (protect\$5 or solder near resist\$4) and resin with seal\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 13:21			
4	BRS	L5	0	(257/616).ccls. and flexible with substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and solder near resist\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 13:28			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Com men ts	Er ro r De fi ni ti on	Er ro rs
5	BRS	L6	6	flexible with substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and solder near resist\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 13:28			
6	BRS	L7	18	("5351145" "5353041" "5489867" "5642127" "5828357" "5917238" "5920221" "6002384" "6057866" "6144355" "6157228" "6166715" "6232939" "6236393" "6256024" "6373458").PN. OR ("6697041").URP N.	US-PGPUB; USPAT; USOCR	2006/05/26 13:30			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
7	BRS	L8	0	(257/E21.515).c cls. and flexible with substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and (protect\$5 or solder near resist\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 13:41			
8	BRS	L9	19	(257/E21.511).c cls. and flexible with substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and (protect\$5 or solder near resist\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 13:42			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
9	BRS	L3	57	("257"/\$).ccls. and flexible with substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and (protect\$5 or solder near resist\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:01			
10	BRS	L10	8	("257"/E21.511) .ccls. and substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and (protect\$5 or solder near resist\$4) and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:02			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
11	BRS	L11	7	(257/E21.504).c cls. and substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and (protect\$5 or solder near resist\$4) and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:03			
12	BRS	L12	48	(257/773- 783).ccls. and substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and (protect\$5 or solder near resist\$4) and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:03			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Com men ts	Er ro r De fi ni ti on	Er ro rs
13	BRS	L13	27	(257/685-698).ccls. and substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and (protect\$5 or solder near resist\$4) and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:03			
14	BRS	L14	6	(257/666).ccls. and substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and (protect\$5 or solder near resist\$4) and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:04			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
15	BRS	L15	8	(257/734).ccls. and substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and (protect\$5 or solder near resist\$4) and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:06			
16	BRS	L16	14	substrate with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and coat\$ with solder near resist\$4 and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:22			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
17	BRS	L17	4	substrate with flexible with chip and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and coat\$ with solder near resist\$4 and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:23			
18	BRS	L18	4	substrate with flexible and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and coat\$ with solder near resist\$4 and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:22			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
19	BRS	L19	4	substrate with flexible with (chip or die) and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and coat\$ with solder near resist\$4 and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:28			
20	BRS	L20	14	substrate with (chip or die) and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and coat\$ with solder near resist\$4 and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:27			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
21	BRS	L21	14	(chip or die) and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and coat\$ with solder near resist\$4 and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:26			
22	BRS	L22	16	(chip or die) and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and coat\$ with solder near (resist\$4 or material) and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:26			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
23	BRS	L24	29	substrate with (chip or die) and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and coat\$ with solder and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:27			
24	BRS	L25	6	substrate with flexible with (chip or die) and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and coat\$ with solder and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:28			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
25	BRS	L23	40	(chip or die) and internal near (electrode or connect\$5) and external near (electrode or connect\$5) and coat\$ with solder and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:42			
26	BRS	L27	163	(chip or die) and (electrode or connect\$5) with (internal or external) and coat\$ with solder adj resist and resin with (seal\$4 or encpsulat\$4) and (flexible near substrate or tape)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:45			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Com men ts	Er ro r De fi ni ti on	Er ro rs
27	BRS	L29	43	(flexible near substrate or tape) with (chip or die) with (electrode or connect\$5) with (internal or external) and coat\$ with solder adj resist and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 14:46			
28	BRS	L28	124	(flexible near substrate or tape) with (chip or die) and (electrode or connect\$5) with (internal or external) and coat\$ with solder adj resist and resin with (seal\$4 or encpsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 15:31			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
29	BRS	L30	18	(flexible near substrate or tape) with (chip or die) and (electrode or connect\$5) with (internal or external) and coat\$ with solder adj resist and resin with (seal\$4 or encpsulat\$4) and (lcd or liquid near crystal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 15:31			
30	BRS	L31	32	(chip or die) and (electrode or connect\$5) with (internal or external) and coat\$ with solder adj resist and resin with (seal\$4 or encpsulat\$4) and (lcd or liquid near crystal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/05/26 15:33			